Silicon Wafer Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Spring Meetings 2026
Friday, April 17, 2026 1:00 PM – 3:30 PM JST
SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

Friday, August 28, 2026 1:00 PM – 4:00 PM JST
SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

Table 1 Meeting Attendees

Italic indicates virtual participants

Co-Chairs: Ryuji Takeda (GlobalWafers Japan), Satoshi Akiyama (Nanoverse Technologies)
SEMI Staff: Akiko Yoshida (SEMI Japan)

Company	*Last*	*First*	*Company*	*Last*	*First*
Advanced Silicon Technology	*Hu*	*Hao*	*Shin-Etsu Handotai*	*Nakasugi*	*Tadashi*
ASML	*Daware*	*Ajinkya*	*Siltronic AG*	*Riedel*	*Frank*
GlobalWafers Japan	Takeda	Ryuji	*Siltronic AG*	*Wirrmann*	*Judith*
Hitachi High-Tech	*Oka*	*Kenji*	*SUMCO*	*Iwanaga*	*Kazuhisa*
Kohzu Precision	Kuwabara	Satoshi	*SUMCO*	*Masada*	*Ayumi*
KOKUSAI ELECTRIC	Matsuda	Mitsuhiro	*SUMCO*	*Nakai*	*Tetsuya*
Nanoverse Technologies	Akiyama	Satoshi			
SELF	Kawai	Naoyuki	SEMI Japan	Koga	Nahoko
SELF	*Yoshise*	*Masanori*	SEMI Japan	Hirabara	Takeaki
Shin-Etsu Handotai	*Kobayashi*	*Takeshi*	SEMI Japan	Yoshida	Akiko

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
6570D	New Standard: Guide for Measuring Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by a Laser-Scattering Tomography Technique	**Passed** with editorial changes

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
7441	SNARF	Int'l AWG TF	Revision with title change of SEMI MF2074-0912 (Reapproved 1023) GUIDE FOR MEASURING DIAMETER OF SILICON AND OTHER SEMICONDUCTOR WAFERS *- Approved by the GCS on January 21, 2026*

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
None			

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
6570	Int'l Test Method TF	New Standard: Guide for Measuring Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by a Laser-Scattering Tomography Technique	2027/04/19
6702	Int'l Test Method TF	Revision of M60: TEST METHOD FOR TIME DEPENDENT DIELECTRIC BREAKDOWN CHARACTERISTICS OF Amorphous SiO2 FILMS FOR Silicon WAFER EVALUATION	2027/01/15

Table 10 SNARF(s) Abolished

#	*TF*	*Title*
7438	Int'l Test Method TF	Line-item Revision to SEMI M95-0925, TEST METHOD FOR NET CARRIER DENSITY AND RESISTIVITY OF SILICON EPITAXIAL LAYER BY CAPACITANCE-VOLTAGE MEASUREMENTS WITH AN EVAPORATED METAL SCHOTTKY DIODE

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
SW20260417-01	SEMI Staff	To forward the ballot adjudication results of Doc.#6570D to the ISC A&R SC for procedural review.
SW20260417-02	Ryuji Takeda	To bring up the Int’l Terminology TF co-leader absence issue to the Silicon Wafer GCS.
SW20260417-03	SEMI Staff	To prepare SNARFs for Line Item Revision to SEMI M67 and M68.
SW20251218-04	SEMI Staff	To send SEMI M95 Major Revision SNARF for two weeks review from the global Silicon Wafer TC members.

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
SW20251218-01	Int’l Test Method TF	To submit M95 Line Item Revision Ballot for Cycle 2, 2026. →Closed. To change from Line Item Revision to Major Revision, the SNARF was canceled.
SW20251218-02	Int’l Test Method TF	To submit Doc.#6570D for Cycle 2, 2026. →Closed
SW20251218-03	Int’l AWG TF	To prepare SNARFs for Line Item Revision to SEMI M67 and M68. →Closed
SW20251218-04	SEMI Staff	To forward the ballot adjudication results of Doc.#7392 to the ISC A&R SC for procedural review. →Closed

1 Welcome, Reminders, and Introductions

Ryuji Takeda (GlobalWafers Japan), called the meeting to order at 1:00 PM JST. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01_Required_Meeting_Element Dec 2024_JPupdated

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve the minutes as written.
By / 2nd: Naoyuki Kawai (Self)/ Satoshi Akiyama (Nanoverse Technologies)
Discussion: None.
Vote: Result: 7-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

Attachment: 02_SW JA TC Minutes_20251218_R2

3 Liaison Report

3.1 *Japan Regional Standards Committee (JRSC)*

Akiko Yoshida (SEMI Japan) reported for the JRSC that the previous meeting was held on April 16, 2026, one day before the Silicon Wafer Japan TC Chapter meeting. Of note:

- Membership were updated and new TC co-chair appointments were approved, including Satoshi Akiyama (Nanoverse Technologies) as a co-chair of the Silicon Wafer Japan TC Chapter.
- The FPD Metrology Japan TC Chapter was dissolved.
- Planning Meeting 2026 will be held on August 27, 2026, inviting all TC co-chairs, TF leaders, and program members recommended by the co-chairs and TF leaders. The meeting aims to deepen participants' knowledge of standardization; this year it will be held in a lecture format with a focus on advanced packaging.

Attachment: 03_JRSC Report_April 2026_R0

3.2 *Global Coordinating Subcommittee (GCS)*

Akiko Yoshida (SEMI Japan) reported for the Silicon Wafer GCS that the Int'l Test Method TF proposed SNARF for Revision (with title change) of SEMI MF2074-0912 (Reapproved 1023), GUIDE FOR MEASURING DIAMETER OF SILICON AND OTHER SEMICONDUCTOR WAFERS and was approved by the GCS.

Attachment: 04_GCS Report_April 2026_R0

3.3 *Silicon Wafer Europe TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the Silicon Wafer EU TC Chapter that there have been no updates from the previous meeting.

Attachment: 05_EU SiW Liaison Report November 2025 2

3.4 *Silicon Wafer North America TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the Silicon Wafer NA TC Chapter that there have been no updates from the previous meeting.

Attachment: 06_NA Si Wafer TC Chapter Liaison Report March 2026

4 SEMI Staff Report

Akiko Yoshida (SEMI Japan) gave the SEMI Staff Report. Of notes:

- 14 new SEMI Standards were published in 2025, including 3 SEMI Standards (SEMI D88, M95, and T27) originated by Japan region.
- Regulations and Procedure Manual were updated and published on April 6. Notable updated points are:
    - Clarification of Removed Standard Status
    - New Rescinded Standard Status
    - Cancellation of the Pending Publication Document
    - New Suspended Standard Status
    - Recording in SEMI Standards Meetings
    - Procedures for Preliminary Subordinate/Primary Standard
    - SNARF Scope Omission

  Members are expected to confirm the details of updated Regulations and Procedure Manual.
- Updating SVM system is in progress to provide fair access to Program Members in China. The system will be released soon.

- Each year at SEMICON Japan, SEMI Japan honors SEMI Standards members for their outstanding contributions. The awards were presented at the SEMI Standards Friendship Party & Awards Ceremony during SEMICON Japan 2025. Last year, the SEMI Japan Honour Award was presented to Tetsuya Nakai (SUMCO) for his many years of service as co-chair of the Silicon Wafer Japan TC Chapter, and the SEMI Japan Special Award was presented to Masanori Yoshise (Self) for his significant contributions to the advancement of SEMI Standards as a co-leader of the Int'l AWG TF.

Attachment: 07_Staff Report_April 2026_R0

5 Ballot Review

NOTE 1: TC Chapter adjudication of ballots is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment file name for each balloted document is provided.

5.1 *Doc.#6570D, NEW STANDARD: GUIDE FOR MEASURING BULK MICRO DEFECT DENSITY AND DENUDED ZONE WIDTH IN ANNEALED SILICON WAFERS BY A LASER SCATTERING TOMOGRAPHY TECHNIQUE*

- This Document passed with editorial changes and will be forwarded to the ISC A&R SC for procedural review.

Attachment: 08_6570D_Ballot Review

6 Subcommittee and Task Force Reports

6.1 *International Advanced Wafer Geometry Task Force*

Satoshi Akiyama (Nanoverse Technologies) reported for the International Advanced Wafer Geometry TF. No Int'l AWG TF meeting had been held since the previous Silicon Wafer Japan TC Chapter meeting in December, therefore, the report was given as a progress update. Of notes:

- As both Doc.#7395 (M67 ESFQR) and Doc.#7390 (M68 ZDD) failed the TC review at the previous TC Chapter meeting, the TF will prepare new SNARFs for Line Item Revision.
- Regarding Doc.#6983A, Revision to SEMI M49-0918 With Title Change To: Guide for Specifying Geometry Measurement Systems for Silicon Wafers for the 130 nm To 3 nm Technology Generations, which was submitted for Cycle 7, 2025 and passed the TC Chapter review at SEMICON Europa, the TF will discuss the comment from Tetsuya Nakai (SUMCO) as a new business.
- The TF will also work on revising SNARF for Revision to SEMI MF2074, which completed two weeks review by the global Silicon Wafer TC members and had some feedback. The TF will revise the SNARF.

Attachment: 10_AWG TF Japan Report_20251217

6.2 *International/ Japan Test Method Task Force*

Ryuji Takeda (GlobalWafers Japan) reported for the International/ Japan Test Method TF. Of notes:

- The TF meeting was held on April 13, 2026.
- Voting results of Doc.#6570D, New Standard: Guide for Measuring Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by a Laser-Scattering Tomography Technique, were reviewed (refer to 5.1 the details of the ballot review result).
- The BMD/ DZ WG started reviewing SEMI M90, which is under 5 year review. The WG will submit the SNARF.
- Drafting Doc.#7437 (Revision to SEMI M85) is in progress by the Chemical Analysis WG.
- The Solid Metal Shottky Epi Wafer Resistivity WG had planned to submit Doc.#7438, Line Item Revision to SEMI M95-0925, in the upcoming Cycle to correct formulas, improve clarity, and address editorial issues.

However, because the revision affected the Scope section, the WG decided to cancel the SNARF and will submit new SNARF for Major Revision to the Silicon Wafer GCS as well as request ballot authorization for Cycle 5.

Motion:	Cancel SNARF 7438, Line-item Revision to SEMI M95-0925, TEST METHOD FOR NET CARRIER DENSITY AND RESISTIVITY OF SILICON EPITAXIAL LAYER BY CAPACITANCE-VOLTAGE MEASUREMENTS WITH AN EVAPORATED METAL SCHOTTKY DIODE.
By / 2nd:	Naoyuki Kawai (Self)/ Satoshi Akiyama (Nanoverse Technologies)
Discussion:	None.
Vote:	Result: 9-Y 0-N. **Motion Passed.**

Attachment: 09_International_Japan Test Method TF meeting minutes April 2026

6.3 *International Advanced Automated Surface Inspection Task Force*

Kenji Oka (Hitachi High-Tech) reported for the International Advanced Automated Surface Inspection TF. Of note:

- The TF is standardizing AFM methods and calibration based on round robin results.
- The test is in its final phase, with evaluation and cross-lab comparison underway and completion expected by May 2026.
- The draft guideline is under internal review and remains on track for presentation at the May SEMI standards meeting.

Attachment: 10_SEMI_IASI status update_20260417

6.4 *International Polished Wafers Task Force*

Ryuji Takeda (GlobalWafers Japan) reported that there had been no specific activities in the International Polished Wafers TF.

6.5 *International Epitaxial Wafers Task Force*

Takeshi Kobayashi (Shin-Etsu Handotai) reported that there had been no specific activities in the International Epitaxial Wafers TF.

6.6 *International Annealed Wafers Task Force*

Ryuji Takeda (GlobalWafers Japan) reported that there had been no specific activities in the International Annealed Wafers TF.

6.7 *International SOI Wafers Task Force*

Akiko Yoshida (SEMI Japan) reported for the International SOI Wafers TF that there had been no specific activities. As Testuya Nakai (SUMCO) stepped down from a co-leader position, the TF is looking for a new TF co-leader.

6.8 *International Terminology Task Force*

Akiko Yoshida (SEMI Japan) reported that the International Terminology TF currently has no activities or co-leaders. Ryuji Takeda will raise this issue with the Silicon Wafer GCS.

7 Old Business

7.1 *Project Period Review*

- SNARF 6570, New Standard: Guide for Measuring Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by a Laser-Scattering Tomography Technique

Motion: Approve one year extension of the project period for SNARF 6570.
By / 2nd: Naoyuki Kawai (Self)/ Satoshi Akiyama (Nanoverse Technologies)
Discussion: None.
Vote: Result: 8-Y 0-N. **Motion Passed.**

- SNARF 6702, Revision of M60: TEST METHOD FOR TIME DEPENDENT DIELECTRIC BREAKDOWN CHARACTERISTICS OF Amorphous SiO2 FILMS FOR Silicon WAFER EVALUATION

Motion: Approve one year extension of the project period for SNARF 6702.
By / 2nd: Naoyuki Kawai (Self)/ Satoshi Akiyama (Nanoverse Technologies)
Discussion: None.
Vote: Result: 9-Y 0-N. **Motion Passed.**

7.2 *5 Year Review Check*

The TC Chapter reviewed the list of the SEMI Standards under 5 year review. As there are a lot of documents which should be reviewed, Akiko Yoshida (SEMI Japan) will remind Kevin Nguyen (SEMI HQ) to maintain those documents.

8 New Business

8.1 *TF Co-leader Issue*

The Int’l AWG TF and the Int’l SOI Wafers TF are both looking for new TF co-leaders. Anyone interested in taking on a TF co-leader role, please contact Akiko Yoshida (SEMI Japan).

9 Action Item Review

9.1 *Open Action Item*

Item #	*Assigned to*	*Details*
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SW20251218-02	Int’l Test Method TF	To submit Doc.#6570D for Cycle 2, 2026. →Closed
SW20251218-03	Int’l AWG TF	To prepare SNARFs for Line Item Revision to SEMI M67 and M68. →Open
SW20251218-04	SEMI Staff	To forward the ballot adjudication results of Doc.#7392 to the ISC A&R SC for procedural review. →Closed

9.2 *New Action Item*

Item #	*Assigned to*	*Details*
SW20260417-01	SEMI Staff	To forward the ballot adjudication results of Doc.#6570D to the ISC A&R SC for procedural review.
SW20260417-02	Ryuji Takeda	To bring up the Int’l Terminology TF co-leader absence issue to the Silicon Wafer GCS.
SW20260417-03	SEMI Staff	To prepare SNARFs for Line Item Revision to SEMI M67 and M68.
SW20251218-04	SEMI Staff	To send SEMI M95 Major Revision SNARF for two weeks review from the global Silicon Wafer TC members.

10 Next Meeting and Adjournment

The next meeting is scheduled for Friday, August 28, 2026 1:00 PM – 4:00 PM JST at SEMI Japan, Tokyo, Japan and via Official Virtual TC Chapter Meeting (Hybrid). Refer to http://www.semi.org/standards for the current list of events.

Adjournment: 15:30 PM JST

Respectfully submitted by:

Akiko Yoshida
SEMI Japan
Phone: +81.50.5805.4605
Email: ayoshida@semi.org

Minutes tentatively approved by:

Ryuji Takeda (GlobalWafers Japan), Co-chair	May 26, 2026
Satoshi Akiyama (Nanoverse Technologies, Co-chair	May 20, 2026

Table 14 Index of Available Attachments[#1]

Title	*Title*
01_Required_Meeting_Element Dec 2024_JPupdated	06_NA Si Wafer TC Chapter Liaison Report March 2026
02_SW JA TC Minutes_20251218_R2	07_Staff Report_April 2026_R0
03_JRSC Report_April 2026_R0	08_6570D_Ballot Review
04_GCS Report_April 2026_R0	09_International_Japan Test Method TF meeting minutes April 2026
05_EU SiW Liaison Report November 2025 2	10_SEMI_IASI status update_20260417

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Akiko Yoshida at the contact information above.